

Semiconductor chips bonded on a substrate

Because of good heat dissipation the bonding agents become conductive when metal powders are added. However, this is only true if the bonding agent is evenly spread. Bubbles in the bonding agent can be imaged non-destructively throughout the silicon chip - Si layer thickness here approx 0.3 mm.

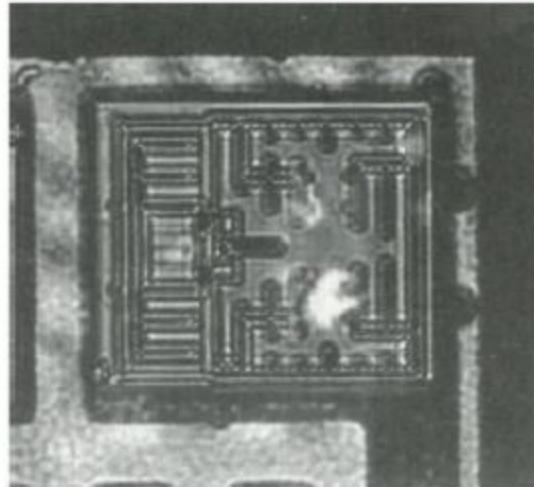


Fig. a: Frequency 60 MHz, Image width: 10 mm

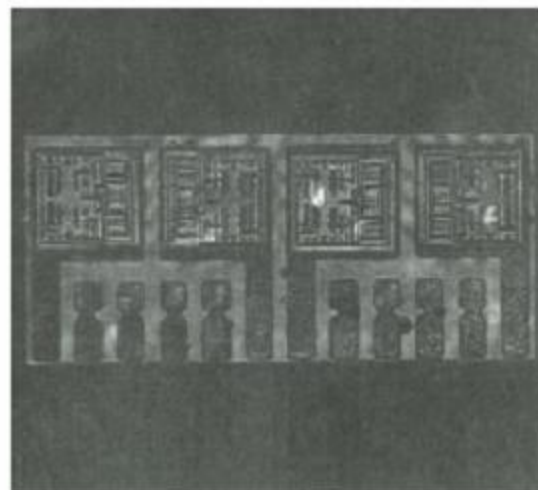


Fig. b: Frequency 60 MHz, Image width: 30 mm